

ConfTool Abstract Submission Procedure

To submit an abstract for EPTC 2023, please follow these steps:

1. Visit the EPTC 2023 website.
2. Click on either the "Authors Resources" tab or the "Registration" tab.
3. Look for the link labelled "Abstract Submission" and click on it.
4. If you have previously created a user ID for any of the past 5 years of EPTC, you can use the same credentials to log in. If you have forgotten your username or password, there is an option to recover them.
5. If you are a new user, please refer to the highlighted section in the screenshot below to register now.

Asia Pacific Region

Conference Time: 12th June 2023, 11:15:05pm Singapore Time

ConfTool Conference Administration

Log in to your account to **submit a contribution**, access your submitted contributions and view the results of the reviewing process. As a reviewer you may enter and edit **reviews**.

If you have not yet created a user account, please do so now.

Please note that the **user accounts from EPTC 2022 were copied**.
Please use your login details from the last event.

Account Login

What is your e-mail address? You can enter your user name if you have an account.

E-mail or user name:

[Forgotten your user name?](#)

Do you already have a password?

☐ No, I would like to **register now**

☐ Yes, my password is:

[Forgotten your password?](#)

Continue

6. Once logged in, click on "Your Submissions" to select an appropriate technical topic.

Overview

11:18:22pm Singapore Time



Your Name

[Logout](#)

Welcome, Your Name

You are logged in as user **Your Name**

You can select from the following options:

Your Submissions

Here you can submit new contributions and manage your submitted contributions.

[Show User Account Details](#)

Here you can access the personal data of your user account.

[Edit User Account Details](#)

Here you can update your personal user data.

[Logout](#)

Please sign out when you are finished to prevent unauthorized access to your account.

[Logout and Return to the Main Website](#)

Sign out and return to the website "25 th Electronics Packaging Technology Conference".

7. Choose the most relevant topic for your abstract, as this selection is crucial for assigning it to the appropriate review committee with the right expertise.

Overview > Your Submissions

Your Submissions

Here you can submit new contributions and manage your submitted contributions.
The number of submissions is limited to 2 per submitting author.

Submit Contribution

To submit your abstracts, please go through the list of technical topics below and click on the most appropriate **highlighted technical topic** for abstract submission.

We encourage you to carefully read the abstract instructions provided under the "Authors' Resources" tab on the EPTC website.

Please submit your abstract in pdf and Word format.

- Advanced Optoelectronics and Displays**
Design, simulation, interconnection, packaging, integration and materials for optoelectronics and novel displays - micro/mini/nano LED, foldable and flexible displays, augmented reality and virtual reality and wearable displays. Silicon and III-V photonics; optical sensors, interconnects, interposers, quantum device packaging; photonics SiP; free-space optical communications, waveguide; automotive photonics, 3D sensing; optoelectronic fiber coupling assembly, materials and reliability; fiber optic transceivers. electro-optical integration.
Deadline: 15th June 2023, 11:59:59pm Singapore Time, **Time left:** 3 days 0 hours
- Advanced Packaging**
Flip-chip, 2.5D & 3D, embedded passives & actives on substrates, chiplets, system in packaging, embedded chip packaging technologies, panel-level packaging, RF, microwave & millimeter-wave, power and rugged electronics packaging. Advanced packaging solutions for 5G, IoT, cloud computing, autonomous vehicles, antennas, sensors, power transfer, EM shielding, RF to THz communications.
Deadline: 15th June 2023, 11:59:59pm Singapore Time, **Time left:** 3 days 0 hours
- Assembly and Manufacturing Technology**
Embedded/hybrid package manufacturing processes; warpage control and management in board-level assembly; thin die/package handling and assembly advance in flexible and printed electronics manufacturing Large/ultra-large package (SiP, SiM, MCP) integration and manufacturing; thermally enhanced packaging and assembly challenges. Additive manufacturing. Panel-level manufacturing and assembly. Heterogeneous integration and manufacturing.
Deadline: 15th June 2023, 11:59:59pm Singapore Time, **Time left:** 3 days 0 hours
- Electrical Simulations & Characterization**
Power plane modeling, Signal integrity analysis by simulations and characterization, 2D/2.5D/3D package level high-speed signal design, Characterization and test methodologies.
Deadline: 15th June 2023, 11:59:59pm Singapore Time, **Time left:** 3 days 0 hours
- Emerging Technologies**
Novel and unique packaging and material technologies for soft and intelligent packaging, flexible hybrid electronics, implantable biosensors and bioelectronics, packaging for extreme harsh environment, green/bio-resorbable packaging; packaging of MEMS & NEMS, packaging for wide bandgap devices, quantum computing, packaging sensing and communication.
Deadline: 15th June 2023, 11:59:59pm Singapore Time, **Time left:** 3 days 0 hours
- Interconnection Technologies**
Au/Ag/Cu/Al Wire-bond / Wedge bond technology, Flip-chip & Cu pillar, Solder alternatives, Cu to Cu, wafer-level bonding & die attachment (Pb-free), Fan-out, panel-level, chiplets, SiP, micro-bump, high I/O thermo-compression/hybrid bonding, fine-pitch/multi-layer RDL, printable interconnects, conductive/ nonconductive adhesives, low-temperature solder, interconnects design and technology for emerging applications.
Deadline: 15th June 2023, 11:59:59pm Singapore Time, **Time left:** 3 days 0 hours
- Materials and Processing**
Photoresist, polymer dielectrics, solder, die-attach, underfill, substrates, lead-frames, materials for wafer & panel-level packaging; harsh environments; wafer bonding/ debond materials; emerging electronic materials & processes; novel solder metallurgies; molding compounds; thermal interface materials; advanced wire-bonding, conductive adhesives. PCB for advanced packaging, assembly processes using newer materials. Substrates in the large/ultra-large package (SiP, SiM, MCP) integration
Deadline: 15th June 2023, 11:59:59pm Singapore Time, **Time left:** 3 days 0 hours
- Mechanical Simulation & Characterization**
Thermal-mechanical interaction, moisture, fracture, fatigue, dynamic impact modelling and characterization. process modelling, etc.
Deadline: 15th June 2023, 11:59:59pm Singapore Time, **Time left:** 3 days 0 hours
- Quality, Reliability & Failure Analysis**
Silicon, component, board and system-level reliability assessment, Interfacial adhesion, Accelerated testing, Failure characterization.
Deadline: 15th June 2023, 11:59:59pm Singapore Time, **Time left:** 3 days 0 hours
- Smart Manufacturing and Equipment Technology**
Smart Manufacturing in packaging, cycle time, data analytics, advanced metrology, machine learning, artificial intelligence, advanced equipment for assembly, packaging and handling Digital Twin and process simulation.
Deadline: 15th June 2023, 11:59:59pm Singapore Time, **Time left:** 3 days 0 hours

- After selecting the relevant technical topic, you will be directed to the abstract submission page.
- Make sure to include all your co-authors, their affiliations, and their email addresses for communication purposes. If you are a student author (only applicable if you are the first author), check the highlighted box for student grant consideration

Submissions
11:32:06pm Singapore Time
Chandra BHESETTI
Logout

Overview > Your Submissions > New Submission

Submission of a Contribution - Step 1

Please complete the form below in order to submit your contribution. All fields marked with an asterisk (*) must be filled in. The next steps will allow you to preview your submission, upload files to the server (if required), and to save your submission.

Once saved, you can return to and update this abstract at any time before the abstract submission deadline (15th June 2023, 11:59:59pm Singapore Time).

Information on This Contribution

Submitting Author	Dr. Chandra BHESETTI (User ID: 1360)
Submission Type / Conference Track	Advanced Optoelectronics and Displays

Information on Author(s)

* Author(s)	First & Middle Name/s	Last Name	E-Mail	Org. Index
1	Chandra	BHESETTI	Bhesetti_Chandra_Rao@	
2				
3				
4				

Add Rows for More Authors

Please list one author per line.
If the contribution has several authors from different organizations, please put an **index number** of the authors' organizations in the right column. The index numbers have to match the line numbers of the organizations below.
Several organizations per author may be separated by commas.
Please make sure that **your co-authors agree to the storage and processing of the submission and their personal data** in accordance with the Data Privacy Agreement before you proceed with the submission.

* Organization(s)	
1	Agency for Science, Technology and Research (A*STAR), Singapore
2	
3	
4	

Add Rows for More Organizations

Please list **every organization only once**. The line number of the organization has to match the **index number** listed above (behind the authors).

Preview List of Authors	Chandra BHESETTI Agency for Science, Technology and Research (A*STAR), Singapore
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Contribution Details

* Title of Contribution	Please add the title of abstract
* Abstract	Please copy and paste the text portion of your abstract. Submit Ms Word or Pdf document as an attachment. <div> Plain text only, do not use HTML in this field. </div>
* Keywords	<div>write keyword</div> Please enter up to five keywords for your contribution here, separated by commas.
Student Contribution	<input type="checkbox"/> This contribution was solely written by students and/or doctoral candidates.
* Please Select	Select "Yes" if you will to "Present in person" OR select "No" if you will to "Present remotely/digitally". <input type="radio"/> Yes <input type="radio"/> No

Remarks on This Contribution

Remark/Message from the Authors to the Program Committee and Chairs	
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10. Please submit your abstract in both MS Word and PDF formats to enable reviewers to highlight their reviews and comments directly on either of the documents before grading it.

Submissions
11:34:45pm Singapore Time
Chandra BHESETTI
Logout

Overview > Your Submissions > New Submission

Submission of a Contribution - Step 2

You now have the option of uploading a file containing your contribution to the server.
If you wish to submit a document at a later time, please select "Save Submission, Upload File(s) Later".
Please note that your file must successfully be uploaded to the server prior to the submission deadline!
Please check your entries before submitting your contribution.

Once saved, you can return to and update this abstract at any time before the abstract submission deadline (15th June 2023, 11:59:59pm Singapore Time).

Contribution Details

Submission Type / Conference Track: Advanced Optoelectronics and Displays

Please add the title of abstract

Chandra BHESETTI

Organization(s): Agency for Science, Technology and Research (A*STAR), Singapore

Submitted by: Dr. Chandra BHESETTI (Agency for Science, Technology and Research (A*STAR), SG), ID: 1300

KeyWords: write keywords

✓ Select "Yes" if you will to "Present in-person" OR select "No" if you will to "Present remotely/digitally".

Abstract

Please copy and paste the text portion of your abstract.
Submit Md Word or Pdf document as an attachment.

Upload File(s) Later

Return to Step 1
Save Submission, Upload File(s) Later

If you wish to upload your file now, please use the form below. You can update your contribution until the submission deadline.

Upload File(s) to Server

Deadline for file uploads	15th June 2023, 11:59:59pm Singapore Time
Time left	3 days 0 hours
Submission Type / Conference Track	Advanced Optoelectronics and Displays
Details	Design, simulation, interconnection, packaging, integration and materials for optoelectronics and novel displays - micro/mini/nano LED, foldable and flexible displays, augmented reality and virtual reality and wearable displays. Silicon and III-V photonics; optical sensors, interconnects, interposers, quantum device packaging; photonics SiP; free-space optical communications, waveguide; automotive photonics, 3D sensing; optoelectronic fiber coupling assembly, materials and reliability; fiber optic transceivers. electro-optical integration.
	The maximum file size allowed is 10 megabytes.
	This limit refers to the sum of all files uploaded at one time. You may also upload file by file if your single files are big.
1st file: pdf	
Please Note	Please upload your Abstract as anonymized PDF document here.
File Types	The following file extensions are allowed: pdf
Select File	Choose a file... No file selected.
	No upload yet.
2nd file: doc, docx	
Please Note	Please upload your Abstract as Word document here.
File Types	The following file extensions are allowed: doc, docx
Second File	Choose a file... No file selected.
	No upload yet.

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